The Shape that Fits the Future

DC3217IYE

Introducing Intel's Next Unit of Computing Kit DC3217IYE

PRODUCT BRIEF

THINK YOU KNOW WHAT SMALL CAN DO? THINK AGAIN.

No more compromising between performance, profile, and price. The Next Unit of Computing (NUC) is a tiny 4"×4"×2" computing device with the power of the 3rd generation Intel® Core™ i3 processor. Its lower power consumption enables innovative system designs and energy-efficient applications in places like digital signage, home entertainment, and portable uses.

SUPERIOR PROCESSING AND GRAPHICS

Visibly smart graphics using the 3rd generation Intel® Core™ i3-3217U processor deliver amazing performance and visually stunning graphics.

STUNNINGLY SMALL FORM FACTOR

The 4"×4"×2" form factor unlocks a world of potential design applications, from digital signage and kiosks to portable innovations.

ADVANCED TECHNOLOGY

The NUC features two SO-DIMM sockets for expandability upto 16 GB of memory, two PCIe* mini-card connectors for flexible support of wireless and SSD configurations, BIOS vault technology, fast boot and the Intel® Visual BIOS. The NUC also supports The Intel® Anti-Theft™ Technology providing hardware intelligence designed to protect your device and its data if its lost or stolen.

Integrated Board	• D33217GKE
Dimensions	• 116.6mm×112.0mm×39.0mm (4.59"×4.41"×1.55")
Cooling	• Active
Drive options	• mSATA
Color options	• Black only
Chassis design	• Aluminum and Plastic
Power Supply	• 19V, 65W DC-DC power adapter
Additional Features	• Antenna for WIFI and Bluetooth pre-assembled for ease of deployment • Front Panel USB 2.0 • VESA mounting bracket included • Integration Guide • 3 year Product Life Cycle

Full PC functionality in its simplest form

Intel® Gigabit Ethernet

Dual HDMI ports supporting
dual independant display capability

Dual USB 2.0 Ports

19V, 65W DC
Power connector

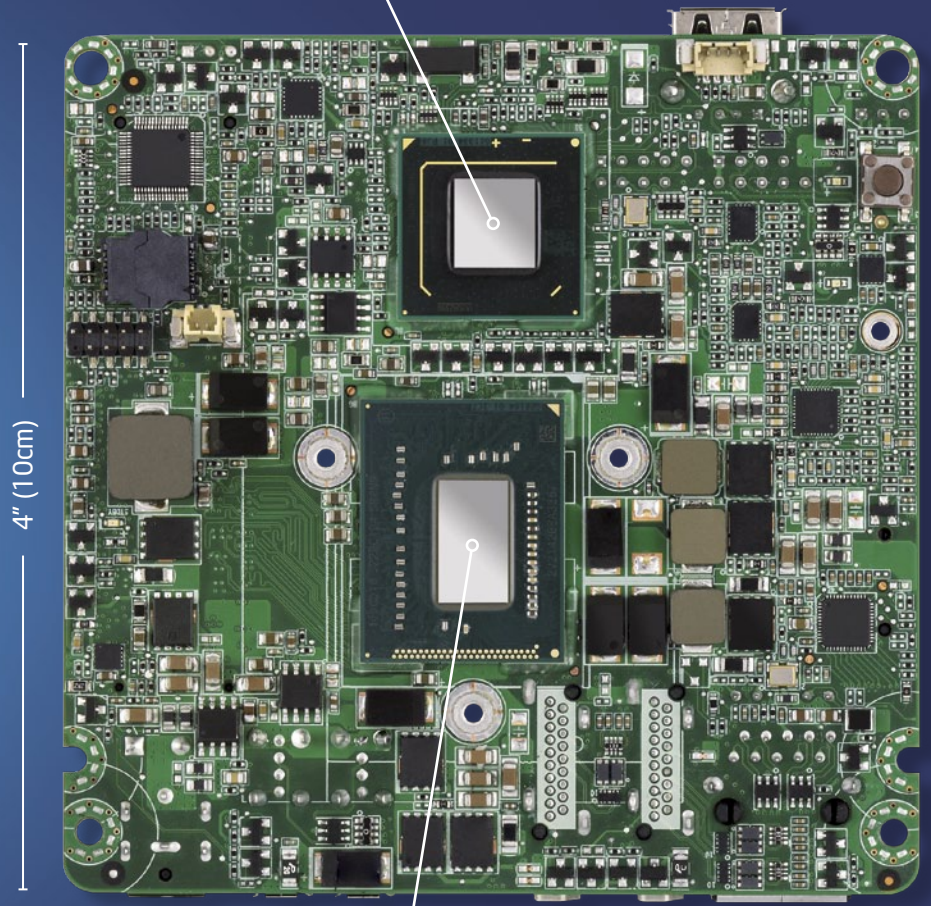
Dual Mini PCIe slots
for expandability

Front Panel USB 2.0 Port

Dual SO-DIMM sockets
for memory expandability upto 16 GB

...with Intel® Desktop Board D33217GKE

Intel® QS77 Express chipset



Intel® Core™ i3-3217U processor

Intel WiDi Wireless Display

Intel ANTI-THEFT TECHNOLOGY

Windows 8 Compatible

Intel® Next Unit of Computing Kit DC3217IYE

Technical Specifications

PROCESSOR

Processor Support

- Intel® Core™ i3 3217U Processor (1.8 GHz, Dual Core processor with 3 MB smart cache)
- Supports Intel® 64 architecture[3]

CHIPSET

- Intel® QS77 Express Chipset

GRAPHICS

- Intel® HD Graphics 4000
- Dual HDMI Ports supporting dual independent display capability

PERIPHERAL CONNECTIVITY

- Integrated Intel 10/100/1000 Network Connection
- Three Hi-Speed USB 2.0 ports (two back panel ports and one front panel port)

EXPANSION CAPABILITIES[2]

- One full length mini-PCIe slot supporting mSATA capability
- One half length mini-PCIe slot with dual USB 2.0 ports routed

SYSTEM BIOS

- Intel® Visual Bios
- 64 Mb Flash EEPROM with Intel® Platform Innovation Framework for EFI Plug and Play
- Advanced configuration and power interface V3.0b, SMBIOS2.5
- Intel® Express BIOS update support

Fast Boot BIOS – Optimized POST for almost instant-on access to PC from power on

SYSTEM MEMORY[1]

Memory Capacity

- Dual-channel DDR3 with two connectors for 1600/1333/1066 MHz memory support (16 GB max)

Memory Voltage

- 1.5V and 1.35V

HARDWARE MANAGEMENT FEATURES

- Processor fan speed control
- Voltage and temperature sensing
- Fan sensor inputs used to monitor fan activity
- ACPI-compliant power management control

INTEL® PRO 10/100/1000 NETWORK CONNECTION

- Low-power design

AUDIO

- Intel® High Definition Audio (Intel HD Audio) via two HDMI 1.4a outputs supporting 8 channel (7.1) digital audio

INDICATORS AND CONTROLS

- HDD LED, Power LED
- Power on/off

MECHANICAL

Chassis Size

- 4.59"×4.41"×1.55" (116.6mm×112.0mm×39.0mm)

Board Size

- 4"×4" (101.6mm×101.6mm)

Baseboard Power Requirements

- DC Power 19V, 65 Watt

ENVIRONMENT

Operating Temperature

- 0°C to +55°C

Storage Temperature

- -20°C to +70°C

COMPLIANCE WITH REGULATIONS AND STANDARDS

Safety Regulations

UL/CSA 60950-1
EN 60950-1
IEC 60950-1
NOM-019-SCFI-1998
GOST-R

EMC Class B Regulations

CISPR 22
CIPSR 24
FCC 47 CFR Part 15, Subpart B
ICES-003
EN 55022
EN 55024
EN 61000-3-2
EN 61000-3-3
IEC/EN 61000-4 Series
VCCI V-3
KN-22
KN-24
CNS 13438

ENVIRONMENTAL COMPLIANCE

Europe RoHS
China RoHS

1 WARNING: Altering PC memory frequency, voltage and/or latency may: (i) reduce system stability and useful life of the system, memory and processor; (ii) cause the processor and other system components to fail; (iii) cause reductions in system performance; (iv) cause additional heat or other damage; and (v) affect system data integrity. Intel has not tested, and does not warranty, the operation of the memory beyond its specifications. Intel assumes no responsibility that the memory, including if used with altered clock frequencies and/or voltages, will be fit for any particular purpose. Check with memory manufacturer for warranty and additional details.

2 System resources and hardware (such as PCI and PCI Express*) require physical memory address locations that can reduce available addressable system memory. This could result in a reduction of as much as 1 GB or more of physical addressable memory being available to the operating system and applications, depending on the system configuration and operating system.

3 64-bit computing on Intel® architecture requires a computer system with a processor, chipset, BIOS, operating system, device drivers, and applications enabled for Intel® 64 architecture. Processors will not operate (including 32-bit operation) without an Intel 64 architecture-enabled BIOS. Performance will vary depending on your hardware and software configurations. See http://developer.intel.com/technology/ intel64/index.htm for more information.

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